

09/868573

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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Mitsuo ZEN

National phase of International Application No.: PCT/JP99/05777

International Filing Date: October 20, 1999

For: SOLDER COATED MATERIAL AND METHOD FOR ITS
MANUFACTURE

5/A
D.G.
11-14-01

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

IN THE CLAIMS:

Please cancel claims 1 - 15 and replace them with the
following:

16. (new) A solder coated material comprising a substrate comprising a difficult to solder material, an electroplated layer of a material having excellent solderability provided on the substrate as base plating and having a thickness of 0.5 - 5 micrometers, and a hot dip solder plating layer provided on the electroplated layer and having a thickness of 10 - 50 micrometers.